IN THE SPECIFICATION

Please substitute the following paragraphs of the Specification as follows.

The paragraph bridging pages 11 and 12:

Alternatively, the embedded electrode 110 can also comprise bipolar electrodes 110a, 110b, as shown in Figure 4a and 4b, that ~~comprises~~ comprise at least two substantially coplanar electrodes that generate substantially equivalent electrostatic clamping forces. A differential electrical voltage is applied to each of the bipolar electrodes 110a, 110b to maintain the electrodes at differential electric potential to induce electrostatic charge in the substrate 55 and electrodes. The bipolar electrodes 110a, 110b can comprise two opposing semicircular electrodes 110a, 110b with an electrical isolation void therebetween that is covered by the dielectric member 115 as shown in Figure 4a. Alternative electrode configurations 110a, 110b include inner and outer rings of electrodes, polyhedra patterned electrodes, or other segmented electrode forms embedded in the dielectric member as shown in Figure 4b.

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Figures 8a to 8f show additional embodiments of the electrical isolators 200 of the present invention. The overlying dielectric member 115 which forms the upper surface of the electrostatic chuck 100 is not shown so that the underlying structures can be shown with more clarity. The dielectric insert 510 illustrated in Figure 8a comprises a plurality of openings 516 leading to a gas flow channel 155. Dielectric insert 510 is shaped to fit into annular ring 180 and comprises a dome-shaped upper surface that, after application of an overlying dielectric member (not shown), can be ground or ablated to expose the openings 516 of the dielectric insert 510 while leaving a portion of the upper surface of the electrode 110 and the insert covered by the overlying dielectric member.

The first full paragraph of page 20:

Another series of dielectric insert designs, shown in Figures 8d through 8f, are positioned in the annular ring 180 fitted in an electrode 110 having two annular trenches 602, 604 therein. In Figure 8d, the dielectric insert 610 comprises a tubular non-porous dielectric sleeve 616 surrounding a porous dielectric insert 618. The dome-shaped upper portion of dielectric insert 610 allows the dielectric member 115 (not shown) to hold it in place. The overlying dielectric member 115 is ground or ablated to expose the porous ~~a~~ dielectric insert 618, as shown in the top view of Figure 8e. This allows heat transfer gas to flow through the channel 155 and porous dielectric insert 618 to the surface of the dielectric member. The non-porous dielectric sleeve 616 is shaped to form a small angle with the adjacent surface 612 of the annular ring 180, allowing deposition of a contiguous coating without voids or cavities at the interface of the sleeve 616 and ring 180. The upper surface of dielectric insert 616 is roughened to provide a strong bond with the dielectric member 115. Preferably, the dielectric sleeve 616 has greater tensile strength and modulus than the insert 618 to provide a more reliable joint between sleeve 616 and annular ring 180. This also reduces formation of voids between dielectric sleeve 616 and ring 180 which can cause flaws in the overlying dielectric coating (not shown). Figure 8f illustrates another dielectric insert 620 that entirely comprises a porous dielectric material, such as the plasma-deactivating material having continuous pore passageways therein. The porosity and pore size distribution of the porous material is selected to reduce formation of plasma in and adjacent to the dielectric insert 620.

The paragraph bridging pages 23 and 24:

Fabrication of this embodiment is shown in Figures 12a through 12f. Figure 12a shows a gas supply channel 155 formed in the electrode 110, and at least one hole or opening 710 is drilled through the surface 706 of the electrode 110 to connect with heat transfer gas flow channel 155, as shown in Figure 12b. The diameter of opening 710 is generally, but not by way of limitation, about 2 mm (0.080 inches) or larger. Although this diameter is not critical, the tolerance of the selected diameter should be held within about ± 0.13 mm (± 0.005 inches). As shown in Figure 12c, a space-holding masking pin 712 is then held in the opening 710 and channel 155 so that the overlying dielectric member 115 can be formed without excessive dielectric material entering into opening 710. This is the reason the tolerance of the diameter of opening 710 should be carefully controlled. The masking ~~Masking~~ pin 712 is preferably constructed from a material which does not adhere to the dielectric member 115, such as a Teflon® (trademark of DuPont Company) masking pin 712. A space ~~Space~~-holding masking pin 712 is generally 3 to 6 diameters high; being sufficiently tall to allow pulling out the pin 712 after forming the dielectric member 115, and sufficiently small to reduce shadowing of the dielectric member 115 around masking pin 712.